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Surface Mountable PTC Resettable Fuse: FSMD2920 Series

1. Summary

(a) RoHS Compliant & Halogen Free

(b) Applications : All high-density boards

(c) Product Features: 2920 Dimension, Surface mountable, Solid state, Faster time to trip than standard SMD devices.

(d) Operation Current: 0.30A~5.00A (e) Maximum Voltage: 6V~60VDC

(f) Temperature Range : -40°C to 85°C

2. Agency Recognition

File No. E211981 UL: C-UL: File No. E211981 TÜV: File No. R50090556

3. Electrical Characteristics (23°C)

Dont	Hold	Trip	Rated	Max	Typical	Max Time to Trip		Resis	tance
Part	Current	Current	Voltage	Current	Power	Current	Time	RMIN	R1MAX
Number	IH, A	IT, A	VMAX, VDC	IMAX, A	Pd, W	Α	Sec	Ohms	Ohms
FSMD030-2920-R	0.30	0.60	60	100	1.5	1.5	3.0	1.000	4.800
FSMD050-2920-R	0.50	1.00	60	100	1.5	2.5	4.0	0.300	1.400
FSMD075-2920-R	0.75	1.50	33	100	1.5	8.0	0.3	0.180	1.000
FSMD075-60-2920-R	0.75	1.50	60	100	1.5	8.0	0.3	0.180	1.000
FSMD100-2920-R	1.10	2.20	33	100	1.5	8.0	0.5	0.090	0.410
FSMD110-60-2920R	1.10	2.20	60	100	1.5	8.0	0.5	0.090	0.410
FSMD125-2920-R	1.25	2.50	33	100	1.5	8.0	2.0	0.050	0.250
FSMD150-2920-R	1.50	3.00	33	100	1.5	8.0	2.0	0.050	0.230
FSMD185-2920-R	1.85	3.70	33	100	1.5	8.0	2.5	0.040	0.150
FSMD200-2920-R	2.00	4.00	16	100	1.5	8.0	4.5	0.035	0.120
FSMD200-24-2920-R	2.00	4.00	24	100	1.5	8.0	5.0	0.035	0.120
FSMD250-2920-R	2.50	5.00	16	100	1.5	8.0	16.0	0.025	0.085
FSMD260-2920-R	2.60	5.20	6	100	1.5	8.0	20.0	0.020	0.075
FSMD260-24-2920R	2.60	5.20	24	100	1.5	8.0	20.0	0.020	0.075
FSMD300-2920-R	3.00	5.20	6	100	1.5	8.0	25.0	0.010	0.048
FSMD300-15-2920R	3.00	5.20	15	100	1.5	8.0	20.0	0.010	0.048
FSMD300-24-2920R	3.00	5.20	24	100	1.5	8.0	20.0	0.010	0.048
FSMD330-2920R	3.30	5.50	24	100	1.5	8.0	20.0	0.010	0.048
FSMD400-16-2920R	4.00	8.00	16	100	1.5	20.0	4.0	0.010	0.040
FSMD500-16-2920R	5.00	10.00	16	100	1.5	20.0	5.0	0.005	0.025

Hold current-maximum current at which the device will not trip at 23°C

I_T=Trip current-minimum current at which the device will always trip at 23℃ still air.

V MAX=Maximum voltage device can withstand without damage at it rated current.(I MAX)

I MAX= Maximum fault current device can withstand without damage at rated voltage (V MAX). Pd=Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.

R_{MIN}=Minimum device resistance at 23°C prior to tripping.

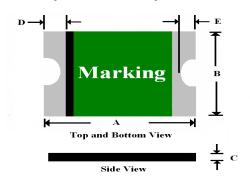
R1MAX=Maximum device resistance at 23°C measured 1 hour after tripping or reflow soldering of 260°C for 20 seconds.

Termination pad characteristics

Termination pad materials: Pure Tin

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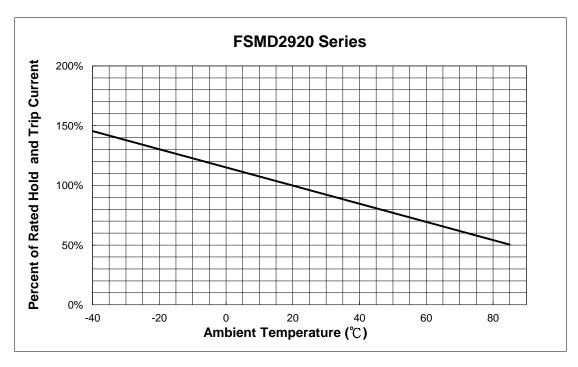
4. FSMD Product Dimensions (Millimeters)



Part		4	E	3	())	E	
Number	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
FSMD030-2920-R	6.73	7.98	4.80	5.44	0.60	1.15	0.50	1.20	0.50	0.90
FSMD050-2920-R	6.73	7.98	4.80	5.44	0.60	1.15	0.50	1.20	0.50	0.90
FSMD075-2920-R	6.73	7.98	4.80	5.44	0.40	1.15	0.50	1.20	0.50	0.90
FSMD075-60-2920-R	6.73	7.98	4.80	5.44	0.60	1.15	0.50	1.20	0.50	0.90
FSMD100-2920-R	6.73	7.98	4.80	5.44	0.40	1.00	0.50	1.20	0.50	0.90
FSMD110-60-2920R	6.73	7.98	4.80	5.44	0.40	1.70	0.50	1.20	0.50	0.90
FSMD125-2920-R	6.73	7.98	4.80	5.44	0.40	0.90	0.50	1.20	0.50	0.90
FSMD150-2920-R	6.73	7.98	4.80	5.44	0.40	0.90	0.50	1.20	0.50	0.90
FSMD185-2920-R	6.73	7.98	4.80	5.44	0.30	0.90	0.50	1.20	0.50	0.90
FSMD200-2920-R	6.73	7.98	4.80	5.44	0.30	0.90	0.50	1.20	0.50	0.90
FSMD200-24-2920-R	6.73	7.98	4.80	5.44	0.20	0.80	0.50	1.20	0.50	0.90
FSMD250-2920-R	6.73	7.98	4.80	5.44	0.30	0.90	0.50	1.20	0.50	0.90
FSMD260-2920-R	6.73	7.98	4.80	5.44	0.30	0.90	0.50	1.20	0.50	0.90
FSMD260-24-2920R	6.73	7.98	4.80	5.44	0.65	1.15	0.50	1.20	0.50	0.90
FSMD300-2920-R	6.73	7.98	4.80	5.44	0.40	0.90	0.50	1.20	0.50	0.90
FSMD300-15-2920R	6.73	7.98	4.80	5.44	0.40	1.15	0.50	1.20	0.50	0.90
FSMD300-24-2920R	6.73	7.98	4.80	5.44	0.65	1.15	0.50	1.20	0.50	0.90
FSMD330-2920R	6.73	7.98	4.80	5.44	0.65	1.15	0.50	1.20	0.50	0.90
FSMD400-16-2920R	6.73	7.98	4.80	5.44	0.40	1.50	0.50	1.20	0.50	0.90
FSMD500-16-2920R	6.73	7.98	4.80	5.44	0.40	1.50	0.50	1.20	0.50	0.90

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5. Thermal Derating Curve



6. Typical Time-To-Trip at 23℃

A = FSMD030-2920-R

B = FSMD050-2920-R

C = FSMD075-2920-R / 075-60-2920-R

D = FSMD100-2920-R

E = FSMD110-60-2920R

F = FSMD125-2920-R

G = FSMD150-2920-R

H = FSMD185-2920-R

I = FSMD200-2920-R / 200-24-2920-R

J = FSMD250-2920-R

K = FSMD260-2920-R / 260-24-2920R

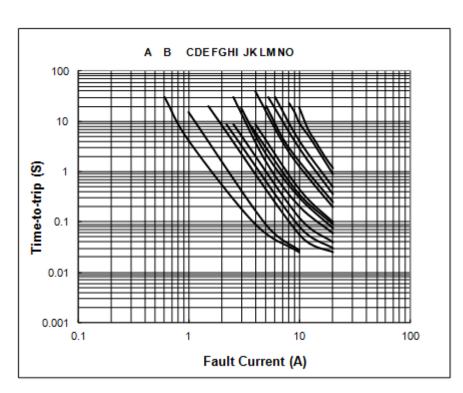
L= FSMD300-2920-R /

300-15-2920R / 300-24-2920R

M = FSMD330-2920R

N = FSMD400-16-2920R

O = FSMD500-16-2920R



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7. Material Specification

Terminal pad material: Pure Tin

Soldering characteristics: Meets EIA specification RS 186-9E, ANSI/J-std-002 Category 3

F200L

Example

075L 60

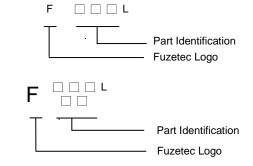
Example

8. Part Numbering and Marking System

Part Numbering System

FSMD \square \square - \square - 2920 R (-R) Voltage Rating **Current Rating**

Part Marking System



Warning: - Each product should be carefully evaluated and tested for their suitability of application. ℯ



- Operation beyond the specified maximum rating or improper use may result in damage and possible electrical arcing and/or flame.
- PPTC device are intended for occasional overcurrent protection. Application for repeated overcurrent condition and/or prolonged trip are not anticipated.

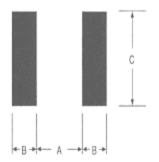
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- Avoid contact of PPTC device with chemical solvent, including some inert material such as silicone based oil, lubricant and etc. Prolonged contact will damage the device performance.

 ✓
- Additional protection mechanism are strongly recommended to be used in conjunction with the PPTC device for protection against
- Avoid use of PPTC device in a constrained space such as potting material, housing and containers where have limited space to accommodate device thermal expansion and/or contraction. ₽

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9. Pad Layouts . Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout for each FSMD2920 device



Pad dimensions (millimeters)						
Device	A Nominal	B Nominal	C Nominal			
All 2920 Series	5.10	2.30	5.60			

Profile Feature Pb-Free Assembly Average Ramp-Up Rate (Tsmax to Tp) 3 °C/second max. Preheat: Temperature Min (Tsmin) 150 °C Temperature Max (Tsmax) 200 ℃ Time (tsmin to tsmax) 60-180 seconds Time maintained above: Temperature(T₁) **217** ℃ Time (t_L) 60-150 seconds Peak/Classification Temperature(Tp): 260 °C Time within 5°C of actual Peak: 20-40 seconds Temperature (tp) Ramp-Down Rate: 6 °C/second max. 8 minutes max. Time 25 °C to Peak Temperature :

Note 1: All temperatures refer to of the package, measured on the package body surface.

Solder reflow

- Due to "Lead Free" nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.
- Recommended max paste thickness is 0.25mm.(Nominal)
- 2. Devices can be cleaned using standard methods and aqueous solvent.
- 3. Rework use standard industry practices.
- 4. Storage Envorinment : < 30°C / 60%RH

Caution:

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- 2. Devices are not designed to be wave soldered to the bottom side of the board.

Reflow Profile

